ON Semiconductor

PRODUCT BULLETIN # 20643

Generic Copy

Issue Date: 15-Sep-2014

TITLE: Change in carrier tape design for WLP6J from without pocket hole to with pocket hole.

PROPOSED FIRST SHIP DATE: 01-Oct-2014

AFFECTED CHANGE CATEGORY(S): Packing material

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor sales office or
<Hidemi.Nomura@onsemi.com><Hiroshi2.Kobayashi@onsemi.com>
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NOTIFICATION TYPE:

ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact <quality@onsemi.com>.

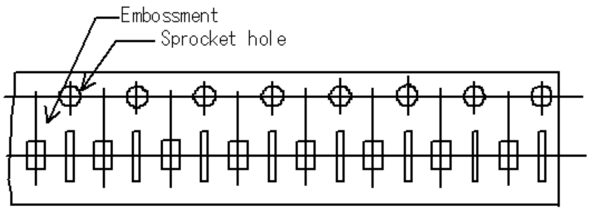
DESCRIPTION AND PURPOSE:

This change is addition of the hole to the emboss carrier tape pocket.
There is no change to raw materials and pocket size.
＊Detail: Refer to below carrier tape drawing.

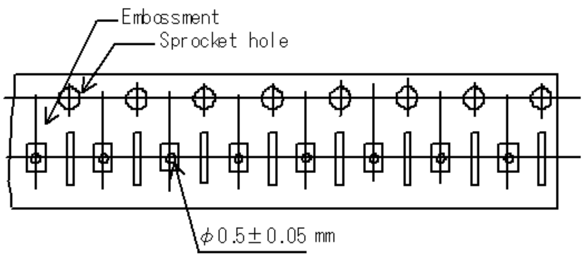
Purpose of this change is the integration of packaging materials in-house.

CHANGE POINT

Before



After



List of affected General Parts:

LE24LA322CSTL2-TFM-E